



ABSOLUTE MAXIMUM RATINGS <sup>(1)</sup>				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
COUPLER				
Isolation test voltage between emitter and detector	$t = 1.0 \text{ s}$	$V_{\text{ISO}}$	5300	$V_{\text{RMS}}$
Creepage distance			$\geq 7$	mm
Clearance distance			$\geq 7$	mm
Isolation thickness between emitter and detector			$\geq 0.4$	mm
Comparative tracking index per DIN IEC 112/VDE 0303, part 1			175	
Isolation resistance	$V_{\text{IO}} = 500 \text{ V}, T_{\text{amb}} = 25 \text{ }^{\circ}\text{C}$	$R_{\text{IO}}$	$\geq 10^{12}$	$\Omega$
	$V_{\text{IO}} = 500 \text{ V}, T_{\text{amb}} = 100 \text{ }^{\circ}\text{C}$	$R_{\text{IO}}$	$\geq 10^{11}$	$\Omega$
Storage temperature range		$T_{\text{stg}}$	- 55 to + 150	$^{\circ}\text{C}$
Ambient temperature range		$T_{\text{amb}}$	- 55 to + 100	$^{\circ}\text{C}$
Junction temperature	max. 10 s, dip soldering	$T_{\text{j}}$	100	$^{\circ}\text{C}$
Soldering temperature <sup>(2)</sup>	max. 10 s, dip soldering: distance to seating plane $\geq 1.5 \text{ mm}$	$T_{\text{sld}}$	260	$^{\circ}\text{C}$

**Notes**

<sup>(1)</sup>  $T_{\text{amb}} = 25 \text{ }^{\circ}\text{C}$ , unless otherwise specified.

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability.

<sup>(2)</sup> Refer to reflow profile for soldering conditions for surface mounted devices (SMD). Refer to wave profile for soldering conditions for through hole devices (DIP).

ELECTRICAL CHARACTERISTICS							
PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT							
Forward voltage	I <sub>F</sub> = 60 mA		V <sub>F</sub>		1.25	1.65	V
Breakdown voltage	I <sub>R</sub> = 10 μA		V <sub>BR</sub>	6			V
Reverse current	V <sub>R</sub> = 6 V		I <sub>R</sub>		0.01	10	μA
Capacitance	V <sub>F</sub> = 0 V, f = 1 MHz		C <sub>O</sub>		25		pF
Thermal resistance			R <sub>thja</sub>		750		K/W
OUTPUT							
Collector emitter capacitance	f = 1 MHz, V <sub>CE</sub> = 5 V		C <sub>CE</sub>		5.2		pF
Collector base capacitance	f = 1 MHz, V <sub>CB</sub> = 5 V		C <sub>CB</sub>		6.5		pF
Emitter base capacitance	f = 1 MHz, V <sub>EB</sub> = 5 V		C <sub>EB</sub>		9.5		pF
Thermal resistance			R <sub>thja</sub>		500		K/W
Collector emitter leakage current	V <sub>CE</sub> = 10 V	SFH600-0	I <sub>CEO</sub>		2	35	nA
		SFH600-1	I <sub>CEO</sub>		2	35	nA
		SFH600-2	I <sub>CEO</sub>		2	35	nA
		SFH600-3	I <sub>CEO</sub>		5	70	nA
COUPLER							
Saturation voltage collector emitter voltage	I <sub>F</sub> = 10 mA, I <sub>C</sub> = 2.5 mA		V <sub>CEsat</sub>		0.25	0.4	V
Capacitance (input to output)			C <sub>IO</sub>			0.6	pF

**Note**

$T_{\text{amb}} = 25 \text{ }^{\circ}\text{C}$ , unless otherwise specified.

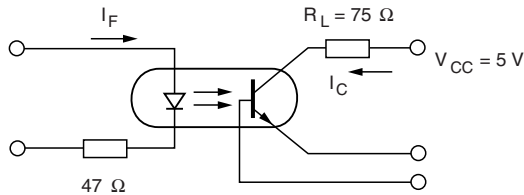
Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.

**CURRENT TRANSFER RATIO**

PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT
$I_C/I_F$ at $V_{CE} = 5.0\text{ V}$	$I_F = 10\text{ mA}$	SFH600-0	CTR	40		80	%
		SFH600-1	CTR	63		125	%
		SFH600-2	CTR	100		200	%
		SFH600-3	CTR	160		320	%
	$I_F = 1\text{ mA}$	SFH600-0	CTR	13	30		%
		SFH600-1	CTR	22	45		%
		SFH600-2	CTR	34	70		%
		SFH600-3	CTR	56	90		%

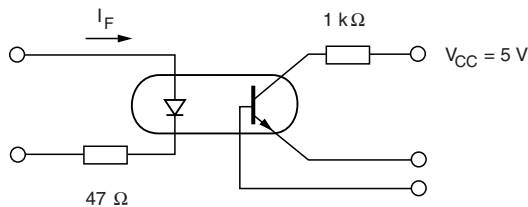
**SWITCHING CHARACTERISTICS**

PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT
<b>NON-SATURATED</b>							
Current	$V_{CC} = 5\text{ V}$ , $R_L = 75\ \Omega$		$I_F$		10		mA
Rise time	$V_{CC} = 5\text{ V}$ , $R_L = 75\ \Omega$		$t_r$		2		$\mu\text{s}$
Fall time	$V_{CC} = 5\text{ V}$ , $R_L = 75\ \Omega$		$t_f$		2.5		$\mu\text{s}$
Turn-on time	$V_{CC} = 5\text{ V}$ , $R_L = 75\ \Omega$		$t_{on}$		3.2		$\mu\text{s}$
Turn-off time	$V_{CC} = 5\text{ V}$ , $R_L = 75\ \Omega$		$t_{off}$		3		$\mu\text{s}$
Cut-off frequency	$V_{CC} = 5\text{ V}$ , $R_L = 75\ \Omega$		$F_{CO}$		250		kHz
<b>SATURATED</b>							
Current		SFH600-0	$I_F$		20		mA
		SFH600-1	$I_F$		10		mA
		SFH600-2	$I_F$		10		mA
		SFH600-3	$I_F$		5		mA
Rise time		SFH600-0	$t_r$		2.5		$\mu\text{s}$
		SFH600-1	$t_r$		3		$\mu\text{s}$
		SFH600-2	$t_r$		3		$\mu\text{s}$
		SFH600-3	$t_r$		4		$\mu\text{s}$
Fall time		SFH600-0	$t_f$		11		$\mu\text{s}$
		SFH600-1	$t_f$		12		$\mu\text{s}$
		SFH600-2	$t_f$		12		$\mu\text{s}$
		SFH600-3	$t_f$		14		$\mu\text{s}$
Turn-on time		SFH600-0	$t_{on}$		3.7		$\mu\text{s}$
		SFH600-1	$t_{on}$		4.5		$\mu\text{s}$
		SFH600-2	$t_{on}$		4.5		$\mu\text{s}$
		SFH600-3	$t_{on}$		5.8		$\mu\text{s}$
Turn-off time		SFH600-0	$t_{off}$		19		$\mu\text{s}$
		SFH600-1	$t_{off}$		21		$\mu\text{s}$
		SFH600-2	$t_{off}$		21		$\mu\text{s}$
		SFH600-3	$t_{off}$		24		$\mu\text{s}$

**TYPICAL CHARACTERISTICS**
 $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified


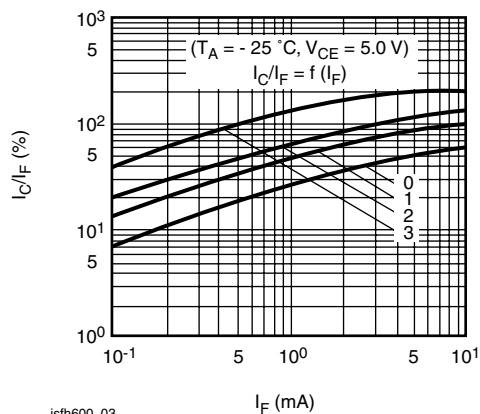
isfh600\_01

Fig. 1 - Linear Operation (without Saturation)



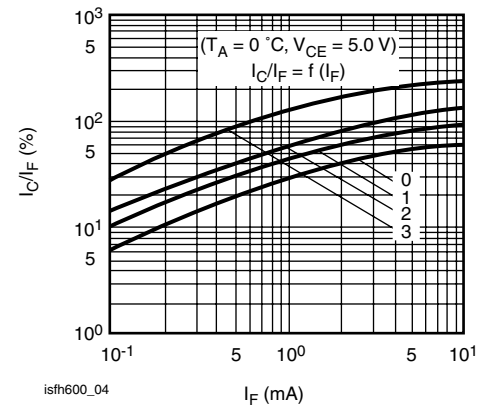
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Fig. 2 - Switching Operation (with Saturation)



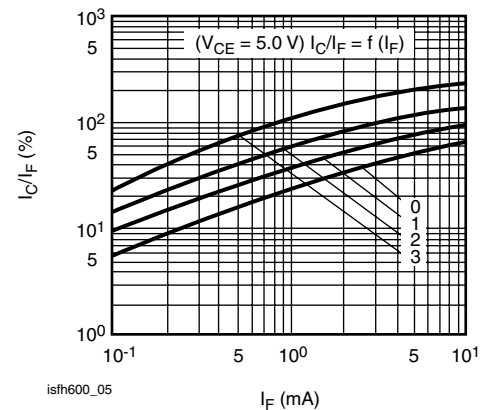
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Fig. 3 - Current Transfer Ratio vs. Diode Current



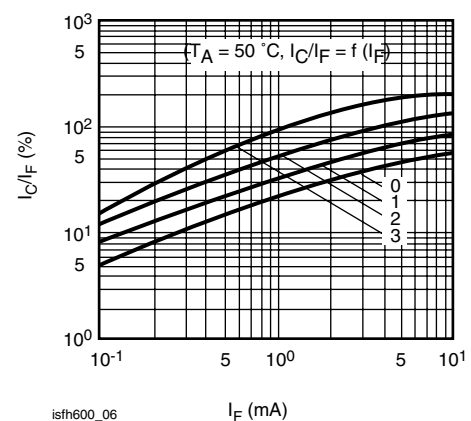
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Fig. 4 - Current Transfer Ratio vs. Diode Current



isfh600\_05

Fig. 5 - Current Transfer Ratio vs. Diode Current



isfh600\_06

Fig. 6 - Current Transfer Ratio vs. Diode Current

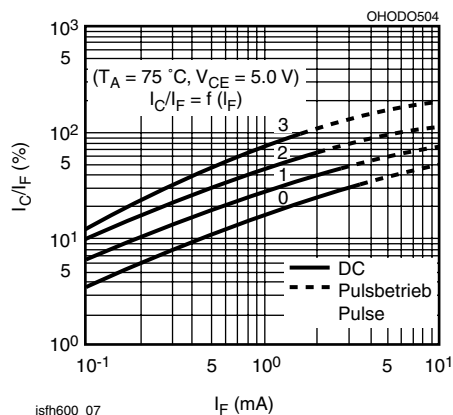


Fig. 7 - Current Transfer Ratio vs. Diode Current

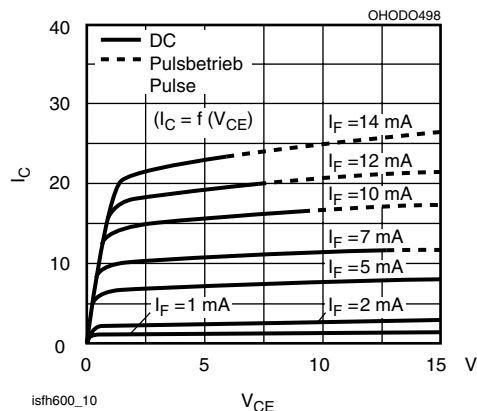


Fig. 10 - Output Characteristics SFH600-2, -3

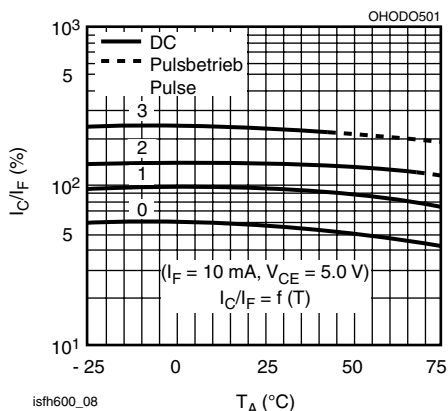


Fig. 8 - Current Transfer Ratio (CTR) vs. Temperature

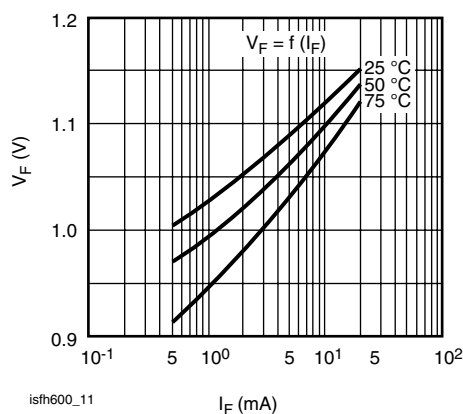


Fig. 11 - Forward Voltage

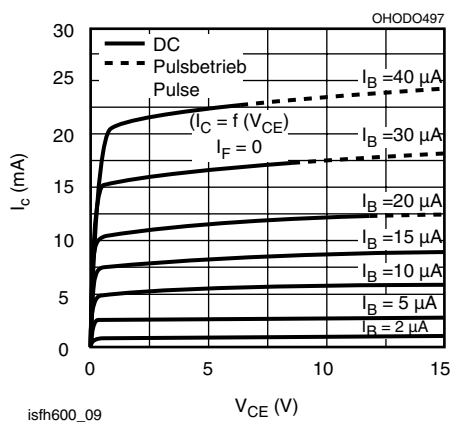


Fig. 9 - Transistor Characteristics SFH600-2, -3

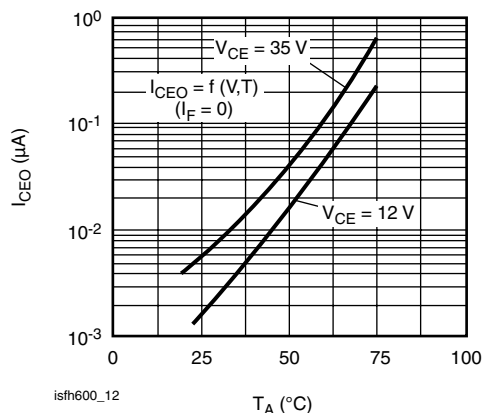


Fig. 12 - Collector Emitter Off-state Current

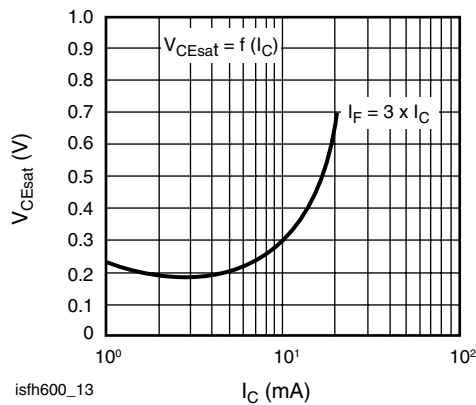


Fig. 13 - Saturation Voltage vs. Collector Current and Modulation Depth SFH600-0

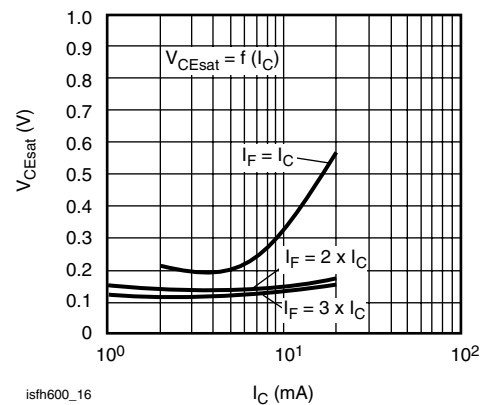


Fig. 16 - Saturation Voltage vs. Collector Current and Modulation Depth SFH600-3

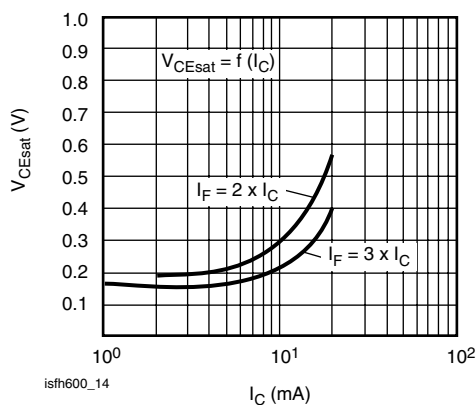


Fig. 14 - Saturation Voltage vs. Collector Current and Modulation Depth SFH600-1

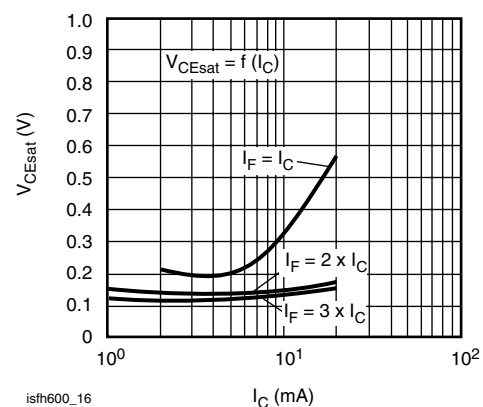


Fig. 17 - Permissible Pulse Load

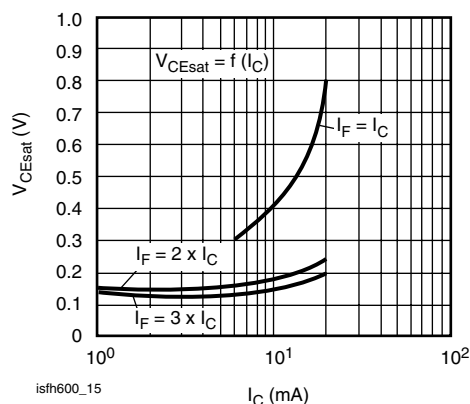


Fig. 15 - Saturation Voltage vs. Collector Current and Modulation Depth SFH600-2

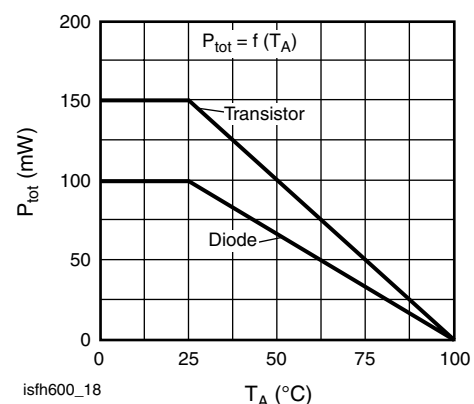


Fig. 18 - Permissible Power Dissipation for Transistor and Diode

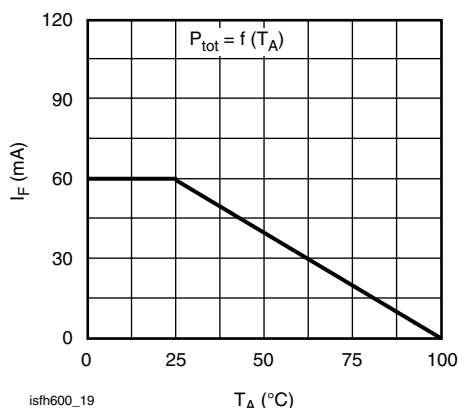


Fig. 19 - Permissible Forward Current Diode

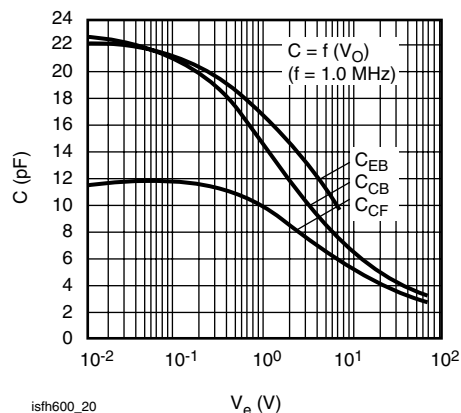
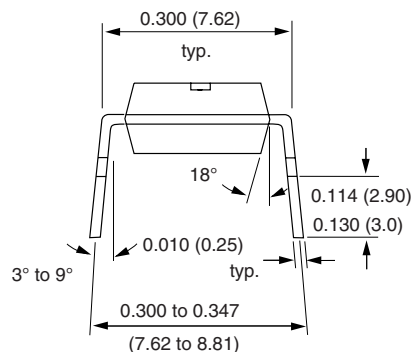
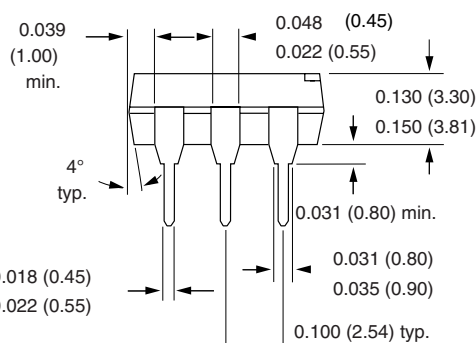
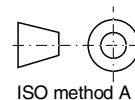
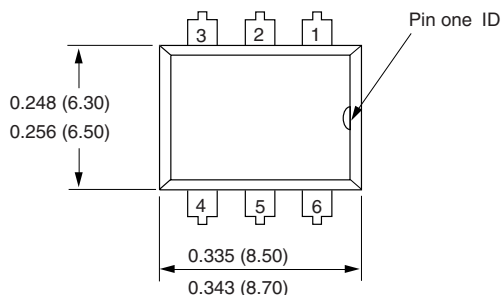
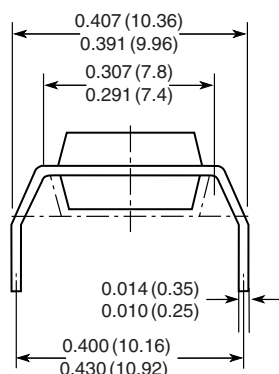
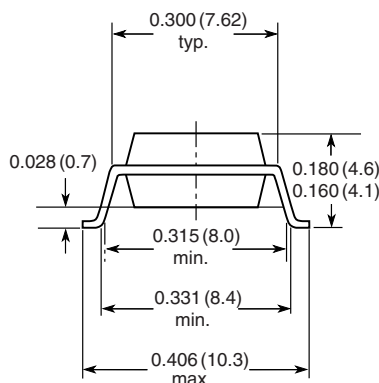
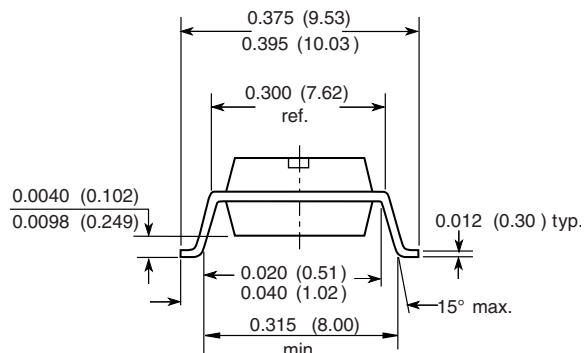


Fig. 20 - Transistor Capacitance

**PACKAGE DIMENSIONS** in inches (millimeters)**Option 6****Option 7****Option 9**

18450

**OZONE DEPLETING SUBSTANCES POLICY STATEMENT**

It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively.
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA.
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design  
and may do so without further notice.

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